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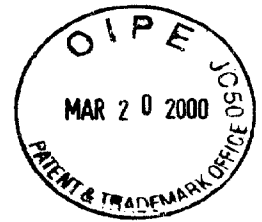


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ASSIGNMENT RECORDATION COVER
-PATENTS ONLY-

To: Honorable Commissioner of Patents and Trademarks:

Please record the attached original document or copy thereof.



1. Name of conveying parties:
 - a) Subhas Bothra
 - b) Dipankar Pramanik
 - c) Calvin T. Gabriel

2. Name and address of receiving party:
 - a) Name: VLSI Technology, Inc.
 - b) Address: 1000 West Maude Avenue, Sunnyvale, CA 94086-2818

3. Nature of conveyance

<input checked="" type="checkbox"/> Assignment	<input type="checkbox"/> Merger
<input type="checkbox"/> Security Agreement	<input type="checkbox"/> Change of Name
<input type="checkbox"/> Other _____	<input type="checkbox"/> License Agreement

Execution Dates: March 9, 2000, February 28, 2000, and February 29, 2000, respectively.

4. Application Number or Patent Number: 09/467,734 filed December 20, 1999

The title of the application is: THIN CAPACITIVE STRUCTURES AND METHODS FOR MAKING THE SAME

5. Please send all correspondence concerning this document to:

03/22/2000 MWGSRMI 00000040 09467734
02 FC:581
40.00 DP

Anthony Josephson
MARTINE PENILLA & KIM, LLP
710 Lakeway Drive, Suite 170
Sunnyvale, CA 94086
Tel. No. (408) 749-6900
Fax No.: (408) 749-6901

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$40.00

<input checked="" type="checkbox"/>	Enclosed
<input checked="" type="checkbox"/>	Authorized to be charged to Deposit Account No. 50-0805 (Order No. VTI1P325)

8. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Date: March 15, 2000

Anthony Josephson, Esq.
Registration No. P45,742



ASSIGNMENT OF PATENT APPLICATION

Whereas we the undersigned inventors have invented certain new and useful improvements as set forth in the patent application entitled:

THIN CAPACITIVE STRUCTURES AND METHODS FOR MAKING THE SAME

(Atty. Docket No: VTIIP325) for which we have executed an application for a United States Letters Patent having U.S. Application No: 09/467,734 and filed on December 20, 1999.

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, We the undersigned inventors hereby:

- 1) Sell, assign and transfer to **VLSI Technology, Inc.**, a Delaware corporation having a place of business at Philips Electronics North America Corporation, 1000 West Maude Ave., Sunnyvale, Ca. 94086-2818, (hereinafter referred to as "ASSIGNEE"), the entire right title and interest in any and all improvements and inventions disclosed in, application based upon, and Patent (including foreign patents) granted upon the information which is disclosed in the above referenced application.
- 2) Authorize and request the Commissioner of Patents to issue any and all Letters Patents resulting from said application or any division, continuation, substitute or reissue thereof to the ASSIGNEE.
- 3) Agree to execute all papers and documents and, entirely at the ASSIGNEE's expense, perform any acts which are reasonably necessary in connection with the prosecution of said application, as well as any derivative and applications thereof, foreign applications based thereon, and/or the enforcement of patents resulting from such applications.
- 4) Agree that the terms, covenants and conditions of this assignment shall inure to the benefit of the ASSIGNEE, its successors, assigns and other legal representative, and shall be binding upon the inventors, as well as the inventors' heirs, legal representatives and assigns.
- 5) Warrant and represent that we have not entered, and will not enter into any assignment, contract, or understanding that conflicts with this assignment.

Signed on the dates indicated beside our signatures.

- | | | |
|----|---------------------------------|-----------------------|
| 1) | Signature: <u>Subhas Bothra</u> | Date: <u>3/9/2000</u> |
| | Typed Name: Subhas Bothra | |
| 2) | Signature: _____ | Date: _____ |
| | Typed Name: Dipankar Pramanik | |
| 3) | Signature: _____ | Date: _____ |
| | Typed Name: Calvin T. Gabriel | |



ASSIGNMENT OF PATENT APPLICATION

Whereas we the undersigned inventors have invented certain new and useful improvements as set forth in the patent application entitled:


THIN CAPACITIVE STRUCTURES AND METHODS FOR MAKING THE SAME

(Atty. Docket No: VTIIP325) for which we have executed an application for a United States Letters Patent having U.S. Application No: 09/467,734 and filed on December 20, 1999.

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- 5) Warrant and represent that we have not entered, and will not enter into any assignment, contract, or understanding that conflicts with this assignment.

Signed on the dates indicated beside our signatures.

- | | | |
|----|--|------------------------|
| 1) | Signature: _____ | Date: _____ |
| | Typed Name: Subhas Bothra | |
| 2) | Signature:  _____ | Date: <u>2/28/2000</u> |
| | Typed Name: Dipankar Pramanik | |
| 3) | Signature: _____ | Date: _____ |
| | Typed Name: Calvin T. Gabriel | |



ASSIGNMENT OF PATENT APPLICATION

Whereas we the undersigned inventors have invented certain new and useful improvements as set forth in the patent application entitled:

THIN CAPACITIVE STRUCTURES AND METHODS FOR MAKING THE SAME

(Atty. Docket No: VT11P325) for which we have executed an application for a United States Letters Patent having U.S. Application No: 09/467,734 and filed on December 20, 1999.

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, We the undersigned inventors hereby:

- 1) Sell, assign and transfer to **VLSI Technology, Inc.**, a Delaware corporation having a place of business at Philips Electronics North America Corporation, 1000 West Maude Ave., Sunnyvale, Ca. 94086-2818, (hereinafter referred to as "ASSIGNEE"), the entire right title and interest in any and all improvements and inventions disclosed in, application based upon, and Patent (including foreign patents) granted upon the information which is disclosed in the above referenced application.
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Signed on the dates indicated beside our signatures.

- | | | |
|----|--|-------------------------------|
| 1) | Signature: _____
Typed Name: Subhas Bothra | Date: _____ |
| 2) | Signature: _____
Typed Name: Dipankar Pramanik | Date: _____ |
| 3) | Signature: <u>Calvin T. Gabriel</u>
Typed Name: Calvin T. Gabriel | Date: <u>29 February 2000</u> |